

Toshiba Intelligent Power Device Silicon Monolithic MOS Integrated Circuit

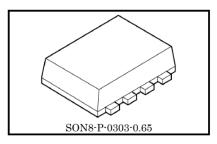
TPD1054F

Low-Side Switch for Solenoid, Mechanical relay and Lamp Drive

1. Description

The TPD1054F is a low-side switch.

The IC has a MOSFET (D-MOS) output which can be directly driven from a CMOS or TTL logic circuit (e.g., an MPU). This IC is a monolithic power IC with intelligent features of protection and diagnostic functions.



Weight: 0.017 g (typ.)

2. Applications

Solenoid drive, mechanical relay drive and lamp drive.

3. Features

- A monolithic power IC with a structure combining a control block and a power MOSFET (D-MOS) on single chip.
- Can directly drive a power load from a CMOS or TTL logic (5 V, 3.3 V input compatible).
- Built-in overcurrent (load short circuit), overtemperature (thermal shutdown) and overvoltage (active clamp) protection circuits.
- Incorporates a diagnosis function that allows diagnosis output to be read externally at overcurrent (load short circuit), overtemperature or load opening.
- Low Drain-Source ON-resistance:

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R_{DS (ON)} = 0.8 \Omega (max) (@V_{DD} = 5 \text{ V}, V_{STBY} = 5 \text{ V}, V_{IN} = 5 \text{ V}, I_{O} = 0.5 \text{ A}, T_{ch} = 25 ^{\circ}\text{C})
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Low Leakage Current:

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I_{DD1} = 10 \mu A \text{ (max) } (@V_{IN} = 0 \text{ V}, V_{STBY} = 0 \text{ V}, V_{DD} = 5 \text{ V}, T_{ch} = -40 \text{ to } 125 \text{ °C})
I_{OL} = 10 \mu A \text{ (max)} (@V_{IN} = 0 \text{ V}, V_{STBY} = 0 \text{ V}, V_{DD} = 5 \text{ V}, V_{OUT} = 8 \text{ to } 16 \text{ V}, T_{ch} = -40 \text{ to } 125 \text{ °C})
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- AEC-Q100 qualified.
- It is a surface-mounted package "PS-8" (named by Toshiba), and the packing is embossed-tape packing.

Note: Due to its MOS structure. This product is sensitive to static electricity.

Start of commercial production 2013-12



4. Block Diagram

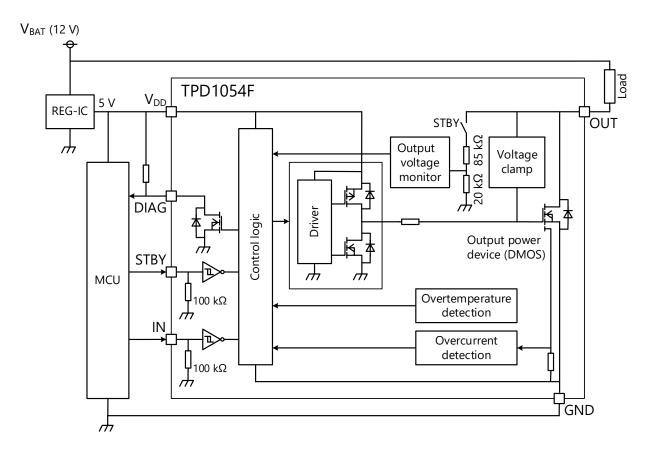


Figure 4.1 Block Diagram

Note: Numerical values in the block diagram are typical values.

5. Pin Assignments

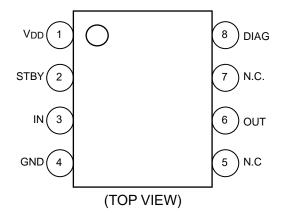


Figure 5.1 Pin Assignments



6. Pin Description

Table 6.1 Pin Description

| Pin No. | Symbol | I/O | Pin Description |
|---------|----------|-----|---|
| 1 | V_{DD} | _ | Power supply pin. |
| 2 | STBY | IN | STBY pin. V _{STBY} =L/Open: I _{DD} ≤10 µA (Standby mode) V _{STBY} =H: Active control |
| 3 | IN | IN | Input pin. The IN pin has an internal pull-down resistor. Even if the IN pin is open, the output will not accidentally turn on. |
| 4 | GND | _ | Ground pin. |
| 5 | N.C | _ | No-Connect pin. (Not connected to the chip.) |
| 6 | OUT | OUT | Output pin. When a load short-circuit causes an overcurrent (1.0A min) to flow into a device, output current is limited in order to protect the IC. |
| 7 | N.C | _ | No-Connect pin. (Not connected to the chip.) |
| 8 | DIAG | OUT | Diagnosis detection pin. It is open drain composition. When Input is "H" (Output on), and Overcurrent or Overtemperature is detected, DIAG becomes low level and it is latched. When input is low level, the state of latch is reset. When Input is "L" (Output off), the output is disconnected (load open is detected), V _{DIAG} =H output. |



7. Functional Description

7.1. Timing chart

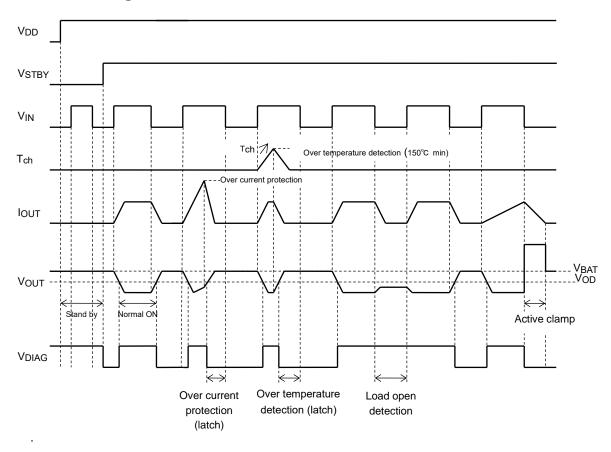


Figure 7.1 Timing chart

7.2. Truth table

Table 7.1 Truth table

| STBY | IN | Output DMOS state | Output voltage Vout (Note 1) | DIAG output | Operating state | | |
|------|----|----------------------|---------------------------------|-------------|------------------------------------|--|--|
| L | L | OFF | Н | Н | Standby made | | |
| L | Н | OFF | Н | Н | Standby mode | | |
| Н | L | OFF | Н | L | Normal OFF | | |
| Н | Н | ON | L | Н | Normal ON | | |
| Н | Н | OFF (latch*) | Н | L (latch*) | Overcurrent (load short) | | |
| Н | Н | OFF (latch*) | Н | L (latch*) | Over temperature | | |
| Н | L | OFF | L | Н | Load open (output is disconnected) | | |

Note 1: H state is Vout>=Vop. L state is Vout<Vop.

^{*}Latch reset condition: VSTBY<VIL or VSTBY<VIL.



8. Absolute Maximum Ratings (Note)

Table 8.1 Absolute Maximum Ratings

(T_a = 25°C unless otherwise specified)

| | | (1a - 20 0 diliciss otherwise specifica) | | | | | |
|---|-------------------------------------|--|--------------------|------|---------------------|--|--|
| Characteristics | Symbol | PIN | Rating | Unit | Note | | |
| Supply voltage | V_{DD} | V_{DD} | -0.3 to 6.0 | V | - | | |
| Input voltage | V _{IN} , V _{STBY} | IN, STBY | -0.3 to 6.0 | V | - | | |
| Diagnosis output voltage | V _{DIAG} | DIAG | -0.3 to 6.0 | V | - | | |
| Diagnosis output current | IDIAG | DIAG | 5.0 | mA | - | | |
| Output voltage | V _{OUT} | OUT | -0.3 to 40.0 | V | - | | |
| Output current | I _{OUT} | OUT | Internally Limited | Α | - | | |
| Dower discipation | P _{D(1)} | - | 0.70 | W | Refer to Figure 9.1 | | |
| Power dissipation | P _{D(2)} | - | 0.35 | W | Refer to Figure 9.2 | | |
| Single pulse active clamp capability (Note 1) | E _{AS} | - | 125 | mJ | - | | |
| Active clamp current | I _{AR} | - | 1.0 | Α | - | | |
| Operating temperature | T _{opr} | - | -40 to 125 | °C | - | | |
| Channel temperature | T _{ch} | - | 150 | °C | - | | |
| Storage temperature | T _{stg} | - | -55 to 150 | °C | - | | |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

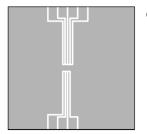
Note 1: Active clamp capability (single pulse) test condition VDD=40 V, Tch=25°C (initial), L=50 mH, IAR=1 A

9. Thermal Characteristics

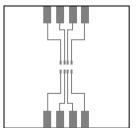
Table 9.1 Thermal characteristics

| Characteristics | Symbol Max | | Unit |
|--|------------------------|--------------------|------|
| Thermal resistance, channel to ambient | Du () | 178.6 (Figure 9.1) | °C/W |
| Thermal resistance, charmer to ambient | R _{th (ch-a)} | 357.2 (Figure 9.2) | C/VV |

 $P_D = (T_{ch} - T_a) / R_{th (ch-a)}$



Glass epoxy board Material: FR-4 25.4 mm × 25.4 mm × 0.8 mm



Glass epoxy board Material: FR-4 25.4 mm × 25.4 mm × 0.8 mm

Figure 9.1 Glass epoxy board (a)

Figure 9.2 Glass epoxy board (b)



10. Operating Ranges

Table 10.1 Operating Ranges

| Characteristics | Symbol | Pin | Condition | Min | Тур. | Max | Unit |
|----------------------------|-----------------------|----------|--|-----|------|-----|------|
| Drain-source clamp voltage | V _{(CL) DSS} | OUT | I _O =1 mA, V _{STBY} =5 V, V _{IN} =0 V | 40 | 45 | 50 | V |
| Operating supply voltage | V _{DD (opr)} | V_{DD} | - | 4.5 | 5.0 | 5.5 | V |

11. Electrical Characteristics

Table 11.1 Electrical Characteristics

(Unless otherwise specified T_{ch} = -40 to 125 °C, V_{DD} = 4.5 to 5.5 V)

| Characteristics | Symbol Pin | | Test circuit | Test condition | Min | Typ. | Max | Unit |
|---------------------------|-----------------------|-----------------|-----------------|---|-----|----------|------|------|
| | | | Circuit | | | (Note 1) | | |
| | I _{DD1} | VDD | - | V _{STBY} =0 V, V _{IN} =0 V, V _{DD} =5 V | - | - | 10 | μA |
| Supply current | I _{DD2} | V _{DD} | - | V _{STBY} =5 V, V _{IN} =0 V, V _{DD} =5 V | - | 0.5 | 2.0 | mA |
| | I _{DD3} | V _{DD} | - | V _{STBY} =5 V, V _{IN} =5 V, V _{DD} =5 V | - | 0.5 | 2.0 | mA |
| Output leakage current | I _{OL1} | OUT | - | V _{STBY} =V _{IL} , V _{IN} =V _{IL} , V _{OUT} =8 to 16 V | | - | 10 | μΑ |
| Output leakage current | I _{OL2} | OUT | - | V _{STBY} =V _{IH} , V _{IN} =V _{IL} , V _{OUT} =8 to 16 V | - | 120 | 300 | μΑ |
| High level input voltage | ViH | IN,STBY | - | - | 2.3 | - | - | V |
| Low level input voltage | V _{IL} | IN,STBY | - | - | - | - | 0.8 | V |
| High level input current | I _{IH} | IN,STBY | - | V _{IN} (V _{STBY})=5 V, V _{DD} =5 V | - | - | 200 | μΑ |
| Low level input current | I _{IL} | IN,STBY | - | V _{IN} (V _{STBY})=0 V, V _{DD} =5 V | -1 | - | 1 | μA |
| Diagnosis output voltage | V_{DL} | DIAG | - | I _{DIAG} =1 mA | - | 0.1 | 0.5 | V |
| Diagnosis output current | I _{DH} | DIAG | - | V _{DIAG} =5.5 V | - | - | 10 | μΑ |
| Drain-source | R _{DS} (ON)1 | OUT | - | I _O =+0.5 A, T _{ch} =25 °C, V _{DD} =5 V, V _{STBY} =V _{IH} , V _{IN} =V _{IH} | - | 0.45 | 0.80 | Ω |
| ON-resistance | R _{DS} (ON)2 | OUT | - | I _O =+0.5 A, T _{ch} =-40 to 125 °C, V _{DD} =5 V, V _{STBY} =V _{IH} , V _{IN} =V _{IH} | - | - | 1.2 | Ω |
| Overtemperature detection | Тот | - | - | V _{STBY} =5 V, V _{IN} =5 V, | 150 | 175 | 200 | °C |
| Overcurrent detection | loc | OUT | - | V _{STBY} =5 V, V _{IN} =5 V, | 1.0 | 2.2 | 3.5 | Α |
| Load open | Rop | OUT | - | V _{STBY} =5 V, V _{IN} =0 V, V _{BAT} =8 to 16 V | 10 | 300 | 1000 | kΩ |
| threshold resistance | ⊿Rop | OUT | - | V _{STBY} =5 V, V _{IN} =0 V, V _{BAT} =8 to 16 V | - | 30 | - | kΩ |
| Diagnosis output | V _{OD} | OUT | - | V _{STBY} =5 V | 2 | 3 | 4 | V |
| threshold voltage | ∠Vod | OUT | - | V _{STBY} =5 V | - | 0.3 | - | V |
| OUT-GND | Rout1 | OUT | - | V _{STBY} =5 V, V _{IN} =0 V, T _{ch} =25 °C | 50 | 105 | 170 | kΩ |
| internal resistance | R _{OUT2} | OUT | - | V _{STBY} =5 V, V _{IN} =0 V, T _{ch} =-40 to 125 °C | 40 | 105 | 200 | kΩ |
| Switching time | t _{on} | OUT | 1 | $V_{STBY}=5$ V, $V_{IN}=0\rightarrow5$ V, $V_{DD}=5$ V, $T_{ch}=25$ °C, $V_{BAT}=12$ V, $R_{L}=60$ Ω | - | 0.5 | 1 | μs |
| Switching time | t _{off} | OUT | 1 | V _{STBY} =5 V, V _{IN} =5 \rightarrow 0 V, V _{DD} =5 V, T _{ch} =25 °C, V _{BAT} =12 V, R _L =60 Ω | - | 0.5 | 1 | μs |

Note 1: The condition of the typical value is $T_{ch}=25^{\circ}C$, $V_{DD}=5V$.



12. Test Circuit

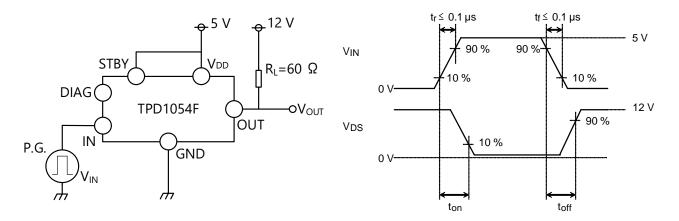


Figure 12.1 Test circuit 1 (Switching time test circuit)

Figure 12.2 Switching time waveforms



13. Characteristic curves

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

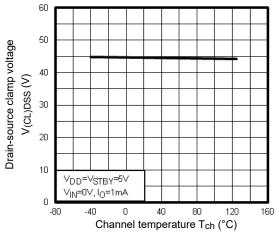


Figure 13.1 V_{(CL)DSS} – T_{ch}

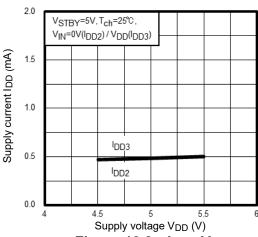


Figure 13.2 $I_{DD} - V_{DD}$

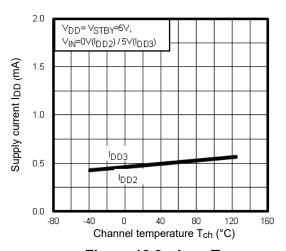


Figure 13.3 I_{DD} - T_{ch}

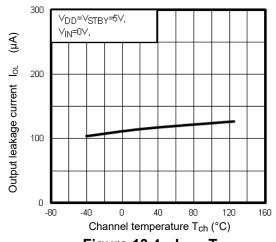


Figure 13.4 I_{OL} – T_{ch}

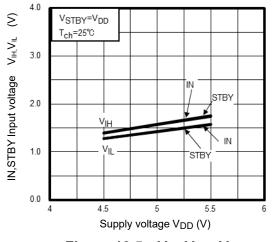


Figure 13.5 V_{IH}, V_{IL} - V_{DD}

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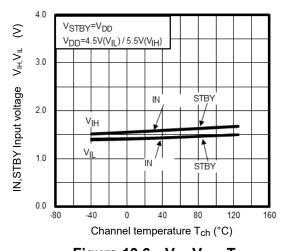


Figure 13.6 V_{IH}, V_{IL} - T_{ch}



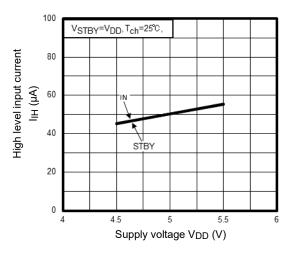


Figure 13.7 I_{IH} –V_{DD}

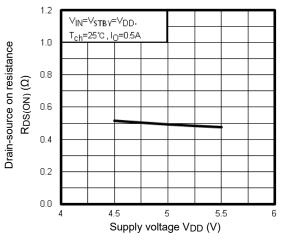


Figure 13.9 $R_{DS(ON)} - V_{DD}$

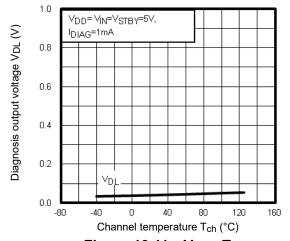


Figure 13.11 V_{DL} - T_{ch}

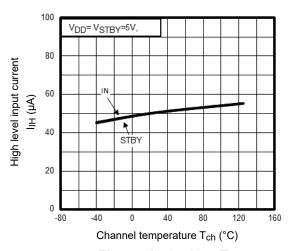


Figure 13.8 I_{IH} – T_{ch}

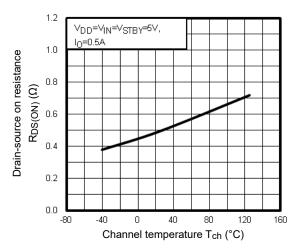


Figure 13.10 $R_{DS(ON)} - T_{ch}$

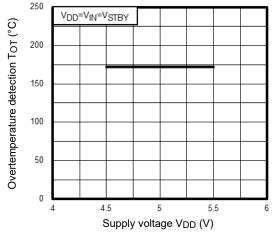


Figure 13.12 $T_{OT} - V_{DD}$



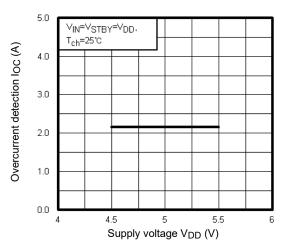


Figure 13.13 Ioc - VDD

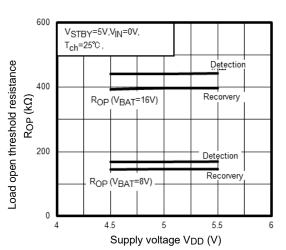


Figure 13.15 $R_{OP} - V_{DD}$

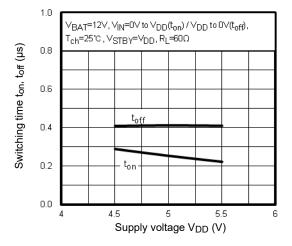


Figure 13.17 t_{on} , $t_{off} - V_{DD}$

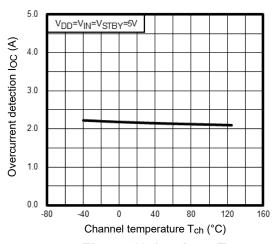


Figure 13.14 $I_{OC} - T_{ch}$

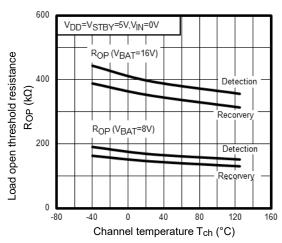


Figure 13.16 R_{OP} – T_{ch}

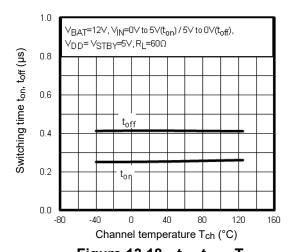


Figure 13.18 t_{on} , $t_{off} - T_{ch}$



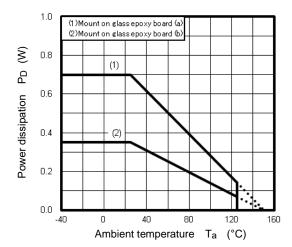
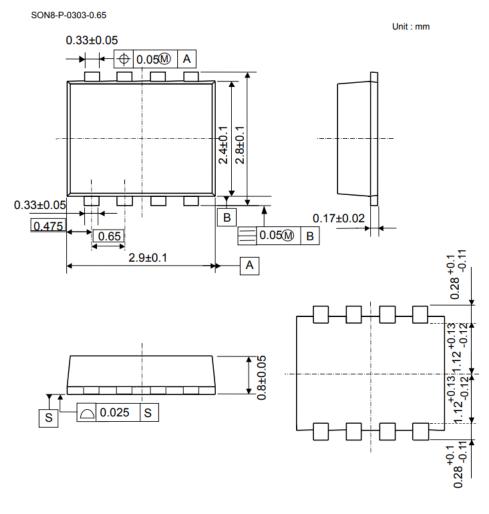


Figure 13.19 $P_D - T_a$



14. Package Information

14.1. Package Dimensions



Weight: 0.017 g (Typ.)

Figure 14.1 Package Dimensions



14.2. Marking

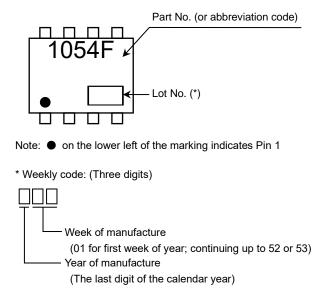


Figure 14.2 Marking

14.3. Land Pattern Dimensions for Reference only

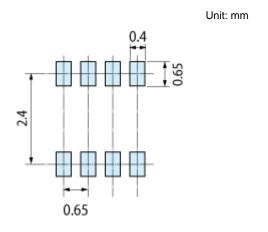


Figure 14.3 Land Pattern Dimensions for Reference only



15. IC Usage Considerations

15.1. Notes on Handling of ICs

The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. None of the multiple ratings can be exceeded. Exceeding the absolute maximum ratings may cause destruction, damage and deterioration, and may result in injury due to explosion or burning.



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